

L Number	Hits	Search Text	DB	Time stamp
1	7877	(high with density) same (capacitor capacitive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:40
2	2994	(ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:41
3	920	((ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))) and (stack stacking multilevel (multi adj level))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:43
4	859	((ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))) and (stack stacking multilevel (multi adj level))) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:43
5	728	(((((ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))) and (stack stacking multilevel (multi adj level)))) and substrate) and (interconnect connection connect interconnection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:44

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1	7877	(high with density) same (capacitor capacitive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:46
2	2994	(ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:41
3	920	((ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))) and (stack stacking multilevel (multi adj level))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:43
4	859	((ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))) and (stack stacking multilevel (multi adj level))) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:43
5	728	(((((ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))) and (stack stacking multilevel (multi adj level))) and substrate) and (interconnect connection connect interconnection))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:45
6	382	(((((ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))) and (stack stacking multilevel (multi adj level))) and substrate) and (interconnect connection connect interconnection)) and ((high with density) with (capacitor capacitive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:47

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1	7877	(high with density) same (capacitor capacitive)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:46
2	2994	(ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:41
3	920	((ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))) and (stack stacking multilevel (multi adj level))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:43
4	859	((ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))) and (stack stacking multilevel (multi adj level)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:43
5	728	((((ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))) and (stack stacking multilevel (multi adj level))) and substrate) and (interconnect connection connect interconnection)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:45
6	382	(((((ic (integrated adj circuit)) and ((high with density) same (capacitor capacitive))) and (stack stacking multilevel (multi adj level))) and substrate) and (interconnect connection connect interconnection)) and ((high with density) with (capacitor capacitive))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/19 21:47